Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: WILLIAM HONG, CHIA-CHE CHUANG, CHI-WEI CHUNG, WEN-CHIH CHIOU, YING-HO CHEN, SYUN-MING JANG

For: <u>COPPER CMP DEFECT REDUCTION BY EXTRA SLURRY POLISH</u>

Enclosed are:						010
X	4 sheets of drawing(s) - formal.					014.8.F
x	An assignment of the invention to Taiwan Semiconductor Manufacturing Co.					_
	An associate power of attorney Applicant claims small entity status					
	Request & Certification under 35 USC 122(b)(2)(b)(i)					
The fili	ng fee has been	calculated as shown be	low:			
	(Col. 1) (Col. 2)			OTHER THAN A SMALL ENTITY		
FOR:		NO. FILED	NO. EXTRA	RATE	FEE	
BASIC	CFEE		$\nearrow$		\$ 770.	
TOTA	L CLAIMS	19 -20=	0	x 18 =	\$0.	
INDE	CLAIMS	2 -3=	0	x 86 =	\$ 0.	
				SUB TOTAL	\$ 770.	
				ASSIGNMENT		
x x	·			\$40.		
	Please charge my Denocit Assessed N. 10 0000 i. i.					
	Please charge my Deposit Account No. 19-0033 in the amount of \$810. A duplicate copy of this sheet is enclosed.					
	The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any					
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	X Any additional filing fees required under 37 CFR §1.16.					
	X Any patent application processing fees under 37 CFR §1.17.					
	Respectfully submitted,					
STERHEND ACKERMAN REG NO 37 761						

EXPRESS MAIL CERTIFICATE

## Express Mail No.EV313927410US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/ox Attorney requests the date of deposit as the Filing Date.

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